

I HIPER CompactPCI® Mezzanine Card

BACKPLANE SYSTEM SLOT CONTROLLER



PART NUMBER: 3U-MEZZ-PCIE

- · Mixed function mezzanine side card for CompactPCI® serial CPU boards
- Based on new mezzanine connectors HSE1/HSE2 (8 x PCle® Gen3)
- 24-lanes PCI® Express Gen3 switch
- Provides gigabit Ethernet I/O (3 x RJ45)
- Provides USB 3.0 front panel I/O (3 x Type A)
- Provides mass storage capability (1 x M.2 NVMe/ SATA, 1 x mSATA)

SPECIFICATION

Backplane Connectors	 CompactPCI® Serial backplane connectors P1, P2, P4, P5, system board pin assignment PCI® Express support for all eight peripheral slots of a secondary CompactPCI® Serial backplane Four links Gen3 x4 (available on peripheral slots 1, 2, 3, 5) Four links Gen2 x1 (available on peripheral slots 4, 6, 7, 8) Can be used with any standard CompactPCI® Serial backplane (system slot left aligned)
PCI Express® Switching	 24-lane 6-port PCI Express® Gen3 packet switch PEX 8724 Upstream 1 x4 link wired to the HSE1 mezzanine connector (CPU card PCH) Downstream 4 x4 links to the CompactPCI® Serial backplane Downstream 1 x4 link to the NVMe SSD M.2 socket 6-lane 6-port PCI Express® Gen2 packet switch PI7C9X2G606PR Upstream 1 x1 link wired to the HSE2 mezzanine connector (CPU card PCH) Downstream 4 x1 links to the CompactPCI® Serial backplane 6-lane 6-port PCI Express® Gen2 packet switch PI7C9X2G606PR Upstream 1 x1 link wired to the HSE2 mezzanine connector (CPU card PCH) Downstream 3 x1 links to the I210 Gigabit Ethernet NICs Downstream 1 x1 link to the TUSB7320 USB controller
Front Panel I/O	 3 x RJ45 Gigabit Ethernet jacks, three individual on-board I210-IT controllers 1000BASE-T, 100BASE-TX, 10BASE-T compliant data transfer rate 3 x USB 3.0 (3.1 Gen1) Type A receptacles Two USB ports via on-Board USB controller, one USB port derived from HSE1 mezzanine connector
Networking	 Three individual networking interface controllers (NIC), based on PCI Express® 1000BASE-T, 100BASE-TX, 10BASE-T connections Intel® 1210-IT -40°C to -85°C operating temperature GbE controllers w. integrated PHY IPv4/IPv6 checksum offload, 9.5KB Jumbo Frame support, EEE Energy Efficient Ethernet IEEE 802.1Qav Audio-Video-Bridging (AVB) enhancements for time-sensitive streams (TSN) IEEE 1588 and 802.1AS packets time stamping for high-precision time synchronization All GbE ports wired via RJ45 front panel connectors
USB	 Upper front panel receptacle wired to HSE1 mezzanine connector (CPU carrier card PCH) Middle and lower connectors wired to PCI Express® dual port USB 3.0 controller TUSB7320 USB 3.1 Gen1 (formerly USB 3.0) xHCI (eXtensible host controller interface) SuperSpeed supported USB 2.0 high-speed, full-speed, low-speed supported 3 x front panel Type-A USB 3.0 host connectors VBUS (+5V) 1.5A high current power switches assigned to front panel connectors
Mass Storage Solutions	 M.2 (formerly known as NGFF) socket for an NVMe type SSD module up to 2280 size PCI Express® Gen3 x4 interface (M-key socket) Socket height 4.2H (double sided module allowed) Capacity up to 2TB as of current Suitable for operating system installation (boot device) Alternate usage with an SATA type SSD B-M key Autosensing analog switch for selection between PCIe® and SATA operation On-Board 6G SATA controller 88SE9170 PCI Express® Mini Card socket, full-size or half-size modules PCI Express® Mini Cards of all styles supported: USB 2.0 and PCIe® based, and mSATA Autosensing analog switch for selection between PCIe® and SATA operation On-Board 6G SATA controller 88SE9170 Suitable for wireless applications e.g. WLAN, Bluetooth or 2G/3G/LTE modem card Micro SIM card holder associated (15mm x 12mm ETSI TS 102 221 V9.0.0, Mini-UICC) Suitable for fieldbus modules e.g. CAN-FD, and industrial Ethernet modules (internet internet modules) Custom specific F/P design for additional pigtail SMB antenna connectors (12HP front or wider) Custom specific F/P design for non-radio applications e.g. CAN-FD (12HP or wider)
Applications	 System expansion with a secondary CompactPCI® Serial backplane Supports PCI Express® on up to eight peripheral slots (4x4 Gen3, 4x1 Gen2) Multi GPU card systems Autonomous driving test equipment Rugged environments

Regulatory & Environmental

- Designed & manufactured in Germany
 ISO 9001 certified quality management
 Custom specific development on request
 Long term availability
 Coating, sealing, underfilling on request
 RoHS compliant 2002/95/EC
 Operating temperature -40°C to +85°C (industrial temperature range)
 Storage temperature: -40°C to +85°C, max. gradient 5°C/min
 Humidity 5% ... 95% RH non condensing
 Altitude -300m ... +3000m
 Shock 15g 0.33ms, 6g 6ms
 Vibration 1g 5-2000Hz
 EC Regulations EN55022, EN55024, EN60950-1 (UL60950-1/IEC60950-1)
 MTBF 44.4 years

The Power to Outperform

Would you like to find out more? Be sure to speak to our on-stand team or contact us via the details here and we would be happy to help.

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